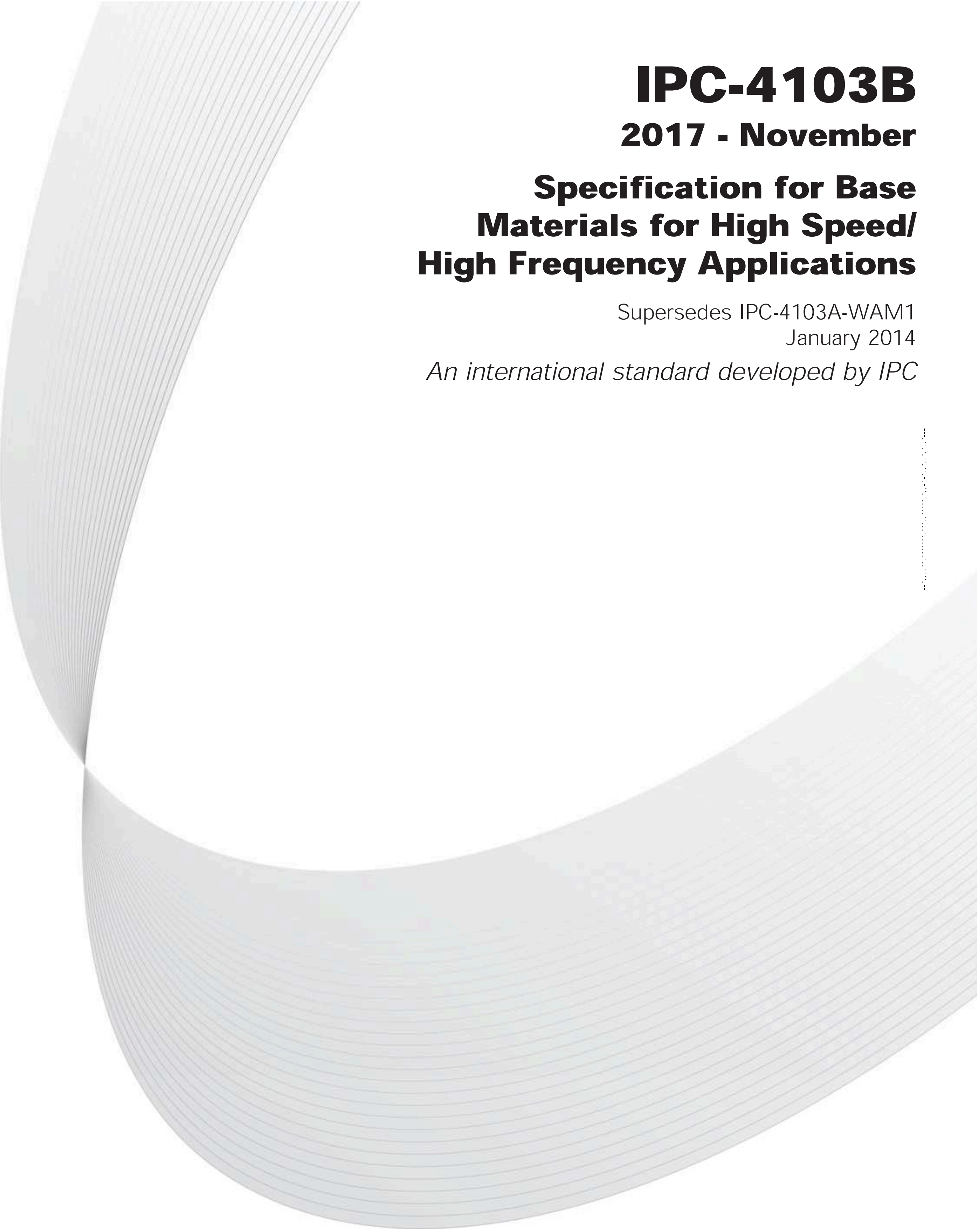

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2017 - November

Specification for Base Materials for High Speed/ High Frequency Applications

Supersedes IPC-4103A-WAM1
January 2014

An international standard developed by IPC

Association Connecting Electronics Industries

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- Contain simple (simplified) language
- Just include spec information
- Focus on end product performance
- Include a feedback system on use and problems for future improvement

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Specification for Base Materials for High Speed/High Frequency Applications

Developed by the High Speed/High Frequency Base Materials Subcommittee (D-23) of the High Speed/High Frequency Committee (D-20) of IPC

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Users of this publication are encouraged to participate in the development of future revisions.

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